L	Hits	Search Text	DB	Time stamp
Number				
1	4	underfill\$4 and semiconductor and	USPAT	2004/06/09
		(carrier adj substrate) and (liquid adj resin)		13:48
2	7	underfill\$4 and semiconductor and	US-PGPUB;	2004/06/09
		(carrier adj substrate) and (liquid adj	EPO; JPO;	13:48
		resin)	DERWENT;	
			IBM_TDB	